

TECHNICAL DATA

Teonex®

Q83

■ Characteristics

Extremely low heat shrinkage type treated by off-line process. Capability for soldering.

■ Typical Applications

FPC, RFID, Heat label, processing film for semiconductor

■ Pretreatment

none

■ Technical Data

Item	Unit	Q83 Type	Test method
Thickness	μm	50	JIS C2151
Tensile strength	MD	MPa	JIS C2318
	TD		
Tensile elongation	MD	90	JIS C2318
	TD	90	
Thermal Shrinkage (150 deg C × 30 mins.)	MD	0.0	JIS C2318
	TD	0.0	
Thermal Shrinkage (200 deg C × 10 mins.)	MD	0.2	JIS C2318
	TD	0.0	
Breakdown voltage	kV/mm	250	JIS C2318
Coefficient of friction	μs	0.4	JIS C7175
	μk	0.3	
Haze	%	15.0	JIS K7136

1.The information contained herein is believed to be reliable and correct.

2.Please refer to the MSDS for product safety data.

3.Information is presented without guarantee or warranty.